

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yoshiyuki YONEDA et al.

Serial Number: 09/442,038

Filed: November 17, 1999

For: DEVICE HAVING RESIN PACKAGE AND METHOD OF PRODUCING THE SAME



Group Art Unit: 2814

Examiner: Thanh V. TRAN

13/c

4-15-02
T. Flowers

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

April 5, 2002

Sir:

In response to the Office Action dated December 7, 2002, extended to April 7, 2002 by a one month Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Claims 2, 5, 7, 10, 15, 18, 20, 21 and 44-46 have been amended as follows:

2. (Twice Amended) A device comprising:

a chip;

a resin package sealing said chip, said resin package having resin projections located on a

mount-side surface of the resin package, said projections projecting from a bottom surface of said

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